US00D563327S

(12) **United States Design Patent** (10) **Patent No.:** **US D563,327 S**
Horio (45) **Date of Patent:** ** **Mar. 4, 2008**

(54) **RESIN-PACKAGED OPTICAL COMMUNICATION MODULE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/253,462**

(22) Filed: **Feb. 7, 2006**

(30) **Foreign Application Priority Data**

Aug. 17, 2005 (JP) 2005-023768

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/165**; D14/358

(58) **Field of Classification Search** D14/240, D14/339, 358, 256, 353, 299, 300; D13/184, D13/123, 199, 101, 165; 379/433.01–433.13, 379/434, 419, 413.04; 220/4.02; 385/16–18, 385/92

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a resin-packaged optical communication module, as shown and described.

DESCRIPTION

FIG. **1** is a front elevation of a resin-packaged optical communication module showing my new design;

FIG. **2** is a top plan view thereof;

FIG. **3** is a bottom plan view thereof;

FIG. **4** is a rear elevation thereof;

FIG. **5** is a left side elevation thereof;

FIG. **6** is a right side elevation thereof; and,

FIG. **7** is a cross-section thereof taken along line **7**—**7** in FIG. **2**.

1 Claim, 2 Drawing Sheets

FIG.1

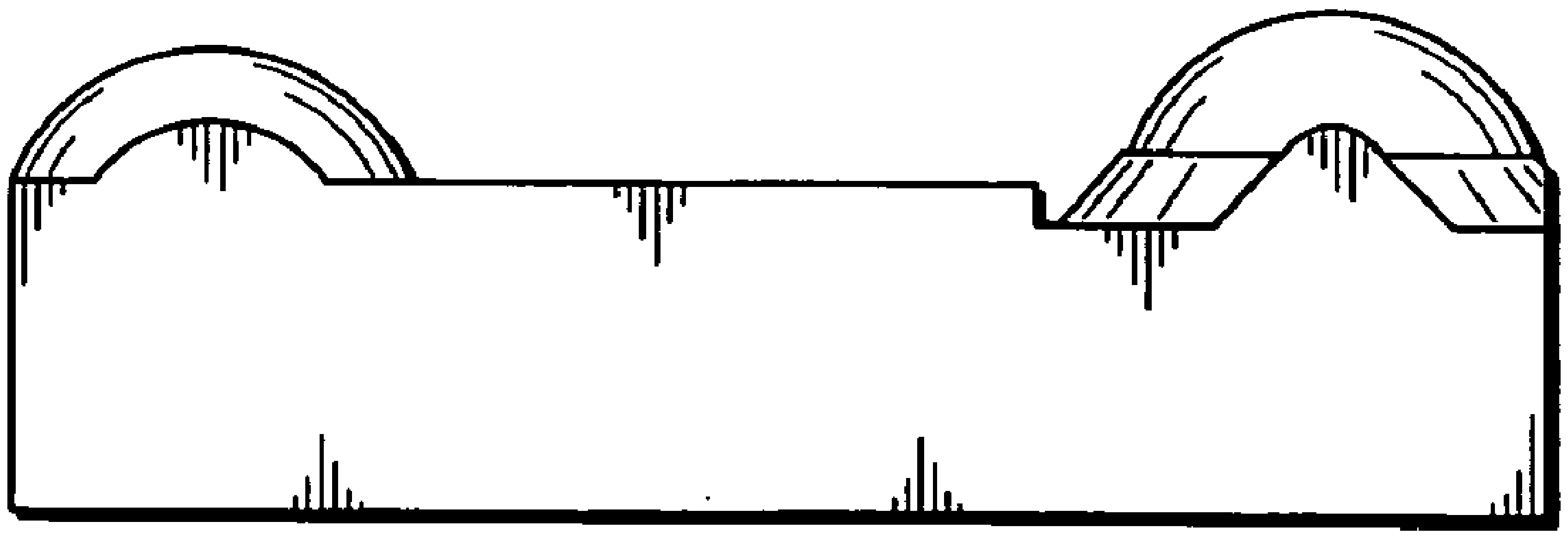

FIG.2

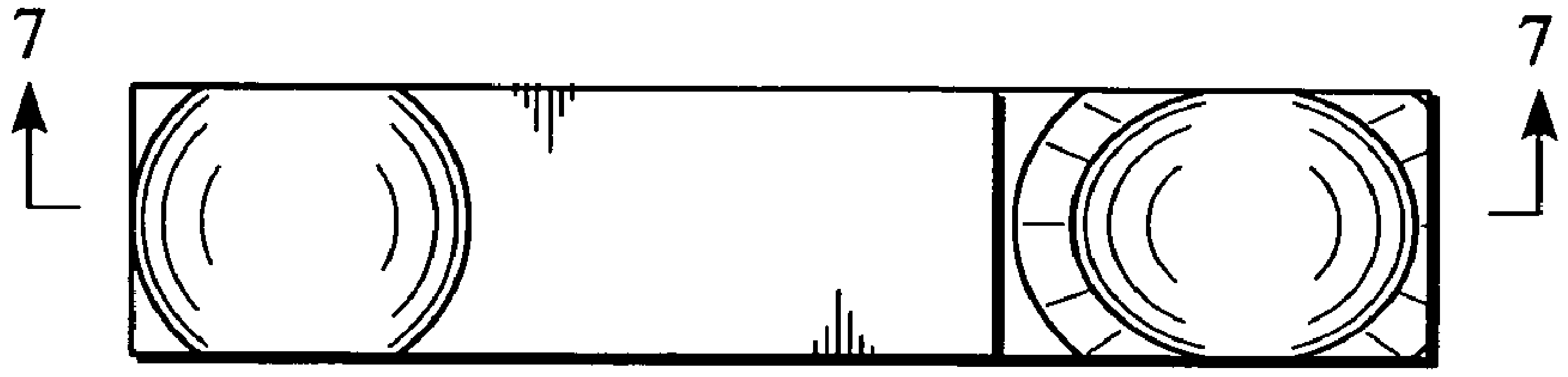

FIG.3

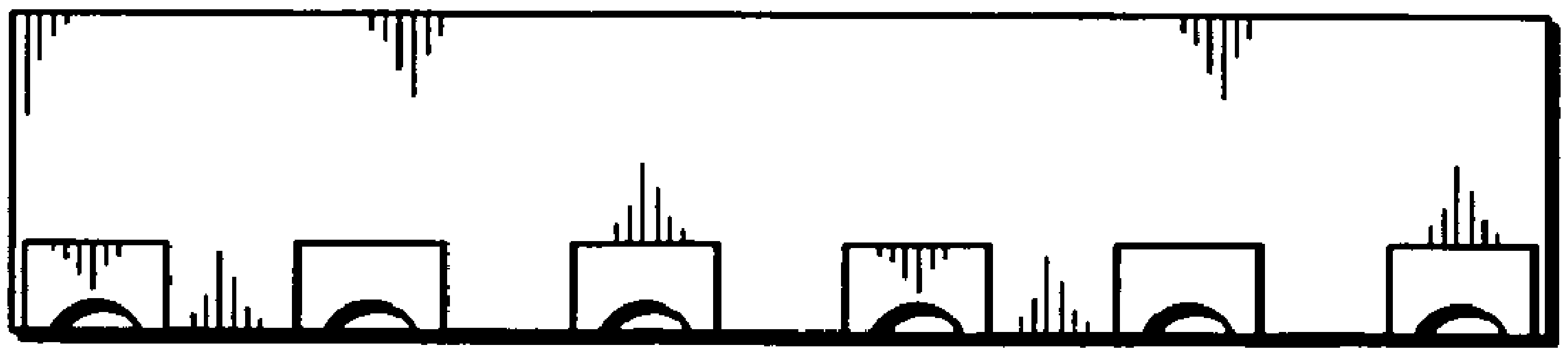

FIG.4

FIG.5

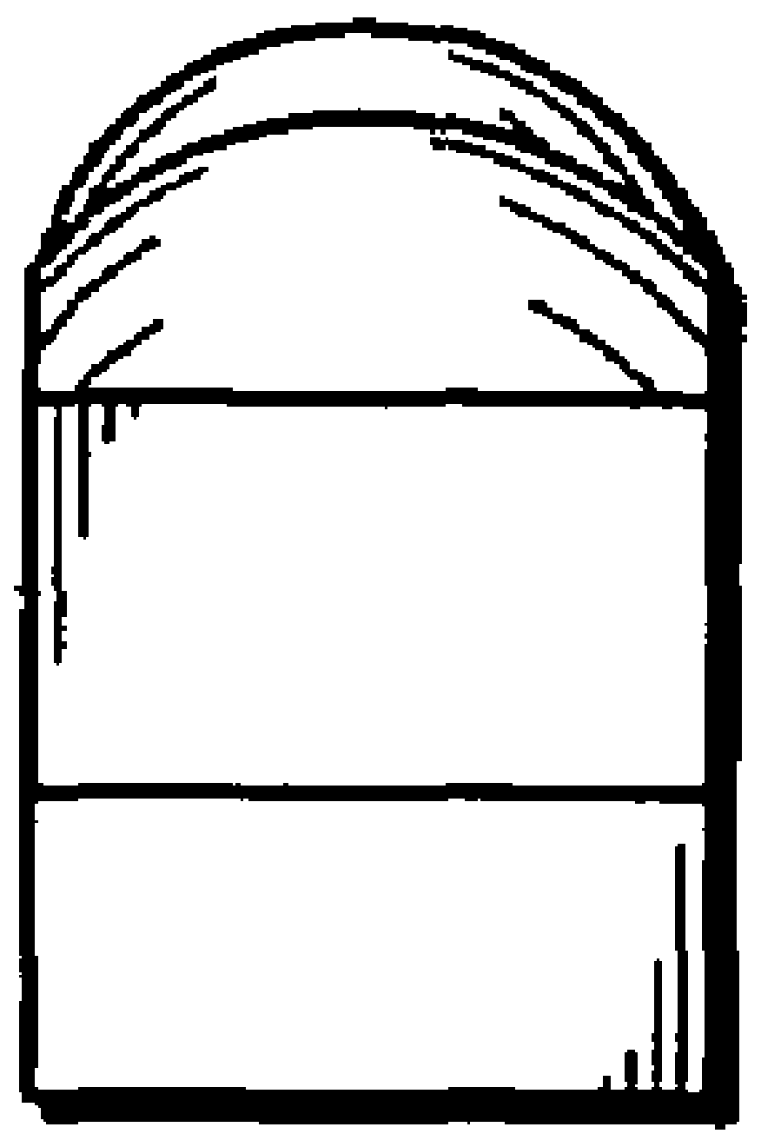

FIG.6

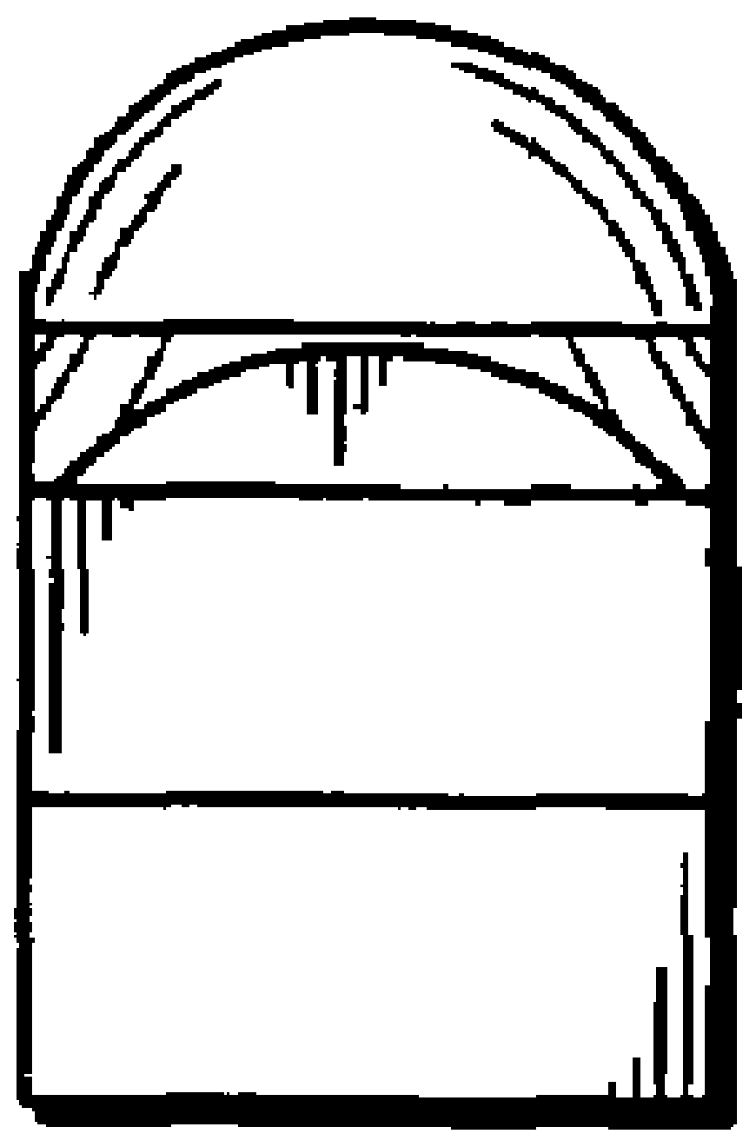

FIG.7